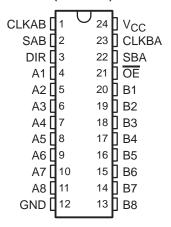
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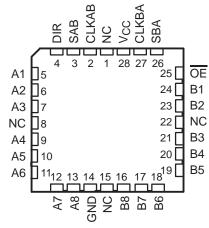
- **Support Mixed-Mode Signal Operation** (5-V Input and Output Voltages With 3.3-V V<sub>CC</sub>)
- **Support Unregulated Battery Operation** Down to 2.7 V
- Typical V<sub>OLP</sub> (Output Ground Bounce) <0.8 V at  $V_{CC} = 3.3 \text{ V}, T_A = 25^{\circ}\text{C}$
- Ioff and Power-Up 3-State Support Hot Insertion

SN54LVTH646 . . . JT OR W PACKAGE SN74LVTH646...DB, DGV, DW, NS, OR PW PACKAGE (TOP VIEW)



- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown
- Latch-Up Performance Exceeds 500 mA Per JESD 17
- **ESD Protection Exceeds JESD 22** 
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

#### SN54LVTH646 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

## description/ordering information

These bus transceivers and registers are designed specifically for low-voltage (3.3-V) V<sub>CC</sub> operation, but with the capability to provide a TTL interface to a 5-V system environment.

#### ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING	
	SOIC - DW	Tube	SN74LVTH646DW	1) /TU040	
	Tape and re		SN74LVTH646DWR	LVTH646	
	SOP - NS	Tape and reel	SN74LVTH646NSR	LVTH646	
-40°C to 85°C	SSOP – DB	Tape and reel	SN74LVTH646DBR	LXH646	
	TCCOD DW	Tube	SN74LVTH646PW	LVIICAC	
	TSSOP – PW	Tape and reel	SN74LVTH646PWR	LXH646	
	TVSOP – DGV	Tape and reel	SN74LVTH646DGVR	LXH646	
	CDIP – JT	Tube	SNJ54LVTH646JT	SNJ54LVTH646JT	
–55°C to 125°C	CFP – W	Tube	SNJ54LVTH646W	SNJ54LVTH646W	
	LCCC – FK	Tube	SNJ54LVTH646FK	SNJ54LVTH646FK	

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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### description/ordering information (continued)

The 'LVTH646 devices consist of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers. Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the 'LVTH646.

Output-enable ( $\overline{OE}$ ) and direction-control (DIR) inputs are provided to control the transceiver functions. In the transceiver mode, data present at the high-impedance port can be stored in either register or in both.

The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The direction control (DIR) determines which bus receives data when  $\overline{OE}$  is low. In the isolation mode ( $\overline{OE}$  high), A data can be stored in one register and/or B data can be stored in the other register.

When an output function is disabled, the input function still is enabled and can be used to store and transmit data. Only one of the two buses, A or B, can be driven at a time.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

These devices are fully specified for hot-insertion applications using  $I_{off}$  and power-up 3-state. The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down. The power-up 3-state circuitry places the outputs in the high-impedance state during power up and power down, which prevents driver conflict.

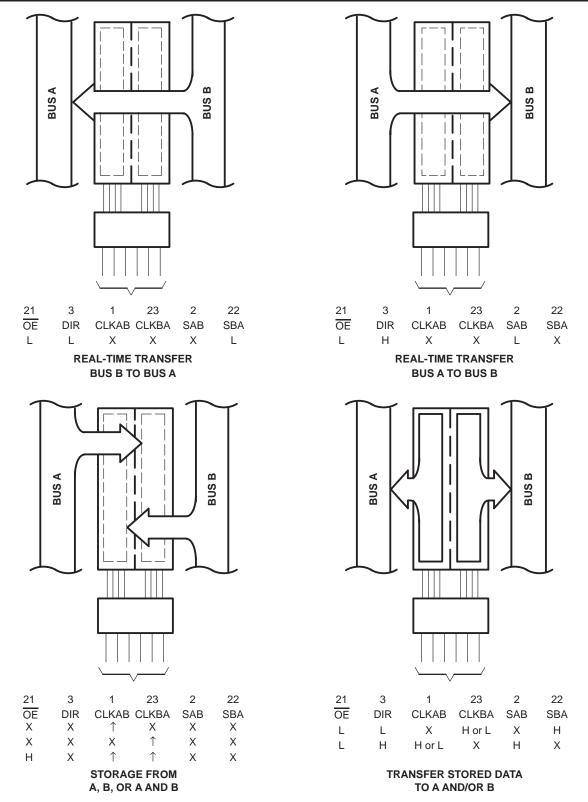
#### **FUNCTION TABLE**

		INP	UTS			DATA	A I/Os	
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1-A8	B1-B8	OPERATION OR FUNCTION
Х	Х	1	Χ	Х	Χ	Input	Unspecified <sup>†</sup>	Store A, B unspecified <sup>†</sup>
Х	Χ	Χ	$\uparrow$	X	Χ	Unspecified <sup>†</sup>	Input	Store B, A unspecified <sup>†</sup>
Н	Х	1	<b>↑</b>	Х	Χ	Input	Input	Store A and B data
Н	Χ	H or L	H or L	Χ	Χ	Input disabled	Input disabled	Isolation, hold storage
L	L	Х	Χ	Х	L	Output	Input	Real-time B data to A bus
L	L	Χ	H or L	Χ	Н	Output	Input	Stored B data to A bus
L	Н	Х	Χ	L	Χ	Input	Output	Real-time A data to B bus
L	Н	H or L	Χ	Н	Χ	Input	Output	Stored A data to B bus

<sup>†</sup> The data-output functions can be enabled or disabled by various signals at  $\overline{\text{OE}}$  and DIR. Data-input functions always are enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.



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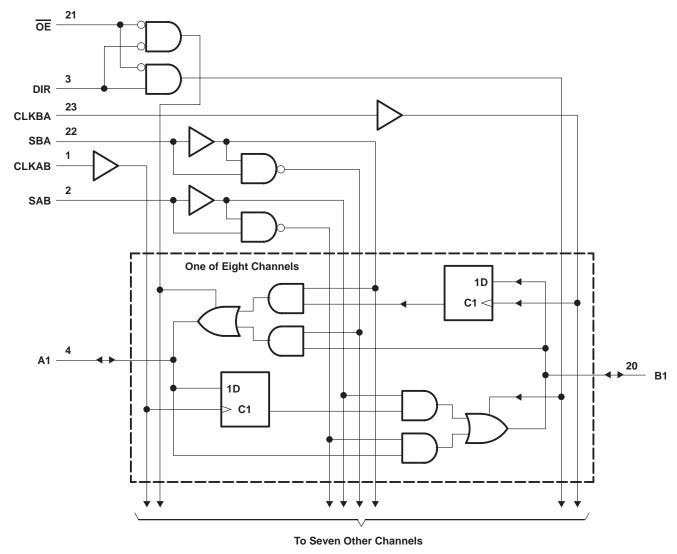
Pin numbers shown are for the DB, DGV, DW, JT, NS, PW, and W packages.

Figure 1. Bus-Management Functions



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## logic diagram (positive logic)



Pin numbers shown are for the DB, DGV, DW, JT, NS, PW, and W packages.

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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		
or power-off state, V <sub>O</sub> (see Note 1)	· · · · · · · · · · · · · · · · · · ·	0.5 V to 7 V
Voltage range applied to any output in the high	state, V <sub>O</sub> (see Note 1)	$-0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Current into any output in the low state, IO: SN	I54LVTH646	96 mA
SN	174LVTH646	128 mA
Current into any output in the high state, IO (see	e Note 2): SN54LVTH646	48 mA
	SN74LVTH646	64 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )		–50 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )		
Package thermal impedance, θ <sub>JA</sub> (see Note 3):		
, on the second of the second		86°C/W
		46°C/W
		65°C/W
		88°C/W
Storage temperature range, T <sub>stg</sub>		

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

- 2. This current flows only when the output is in the high state and  $V_O > V_{CC}$ .
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.

## recommended operating conditions (see Note 4)

			SN54LV	TH646	SN74LV	TH646	LINUT
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		2.7	3.6	2.7	3.6	V
VIH	High-level input voltage		2		2		V
V <sub>IL</sub>	Low-level input voltage			0.8		8.0	V
VI	Input voltage			5.5		5.5	V
loн	High-level output current			-24		-32	mA
lOL	Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		10		10	ns/V
Δt/ΔV <sub>CC</sub>	Power-up ramp rate		200		200		μs/V
T <sub>A</sub>	Operating free-air temperature		-55	125	-40	85	°C

NOTE 4: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

				SN	54LVTH6	646	SN	-1.2  CC-0.2  2.4  2  0.2  0.5  0.4  0.5  ±1  10  20  1  -5  ±100  75  -75  ±500  ±100  0.19  5  0.19	346	
PAF	RAMETER	TEST CO	ONDITIONS	MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	UNIT
VIK		$V_{CC} = 2.7 \text{ V},$	I <sub>I</sub> = -18 mA			-1.2			-1.2	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V},$	I <sub>OH</sub> = -100 μA	VCC-0	.2		VCC-0	.2		
		$V_{CC} = 2.7 \text{ V},$	$I_{OH} = -8 \text{ mA}$	2.4			2.4			V
VOH		V 2.V	$I_{OH} = -24 \text{ mA}$	2						V
		VCC = 3 V	$I_{OH} = -32 \text{ mA}$				2			
		V 27V	I <sub>OL</sub> = 100 μA			0.2			0.2	
		V <sub>CC</sub> = 2.7 V	I <sub>OL</sub> = 24 mA			0.5			0.5	
\/-·			I <sub>OL</sub> = 16 mA			0.4			0.4	V
$V_{OL}$		\/ 2 \/	$I_{OL} = 32 \text{ mA}$			0.5			0.5	V
		VCC = 3 V	I <sub>OL</sub> = 48 mA			0.55				
			I <sub>OL</sub> = 64 mA						0.55	
	Control inputs	$V_{CC} = 3.6 \text{ V},$	$V_I = V_{CC}$ or GND			±1			±1	
	Control inputs	$V_{CC} = 0 \text{ or } 3.6 \text{ V},$	V <sub>I</sub> = 5.5 V			10			10	
lį			V <sub>I</sub> = 5.5 V			20			20	μΑ
	A or B ports‡	V <sub>CC</sub> = 3.6 V	VI = VCC			1			1	
			V <sub>I</sub> = 0			-5			<b>-</b> 5	
l <sub>off</sub>		$V_{CC} = 0$ ,	$V_I$ or $V_O = 0$ to 4.5 $V$						±100	μΑ
		V 2V	V <sub>I</sub> = 0.8 V	75			75			
l <sub>l(hold)</sub>	A or B ports	V <sub>CC</sub> = 3 V	V <sub>I</sub> = 2 V	-75			-75			μΑ
		V <sub>CC</sub> = 3.6 V§,	$V_{I} = 0 \text{ to } 3.6 \text{ V}$						±500	
IOZPU		$\frac{V_{CC}}{OE} = 0$ to 1.5 V, $V_{O} = 0$	0.5 V to 3 V,			±100			±100	μΑ
IOZPD		$\frac{V_{C}C}{OE}$ = 1.5 V to 0, $V_{O}$ =	0.5 V to 3 V,			±100			±100	μΑ
		V <sub>CC</sub> = 3.6 V,	Outputs high			0.19			0.19	
ICC		$I_{O} = 0$ ,	Outputs low			5			5	mA
		$V_I = V_{CC}$ or GND	Outputs disabled			0.19			0.19	
ΔICC¶		V <sub>CC</sub> = 3 V to 3.6 V, On Other inputs at V <sub>CC</sub> or			_	0.2		_	0.2	mA
Ci		V <sub>I</sub> = 3 V or 0			4			4		pF
C <sub>io</sub>		V <sub>O</sub> = 3 V or 0			9			9		pF

 $<sup>^{\</sup>mbox{\scriptsize †}}$  All typical values are at VCC = 3.3 V, TA = 25°C.



<sup>‡</sup> Unused terminals at V<sub>CC</sub> or GND

<sup>§</sup> This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

This is the increase in supply current for each input that is at the specified TTL voltage level, rather than VCC or GND.

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# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 2)

				SN54L\	/TH646			SN74L\	/TH646		
			V <sub>CC</sub> =	3.3 V 3 V	VCC =	2.7 V	V <sub>CC</sub> =	3.3 V 3 V	VCC =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency			150		150		150		150	MHz
t <sub>W</sub>	Pulse duration, CLK high or low		3.3		3.3		3.3		3.3		ns
	Setup time,	Data high	1.3		1.6		1.2		1.5		
tsu	A or B before CLKAB↑ or CLKBA↑	Data low	1.9		2.6		1.6		2.2		ns
t <sub>h</sub>	Hold time, A or B after CLKAB↑ or CLk	KBA↑	1.2		1.2		0.8		0.8		ns

# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 2)

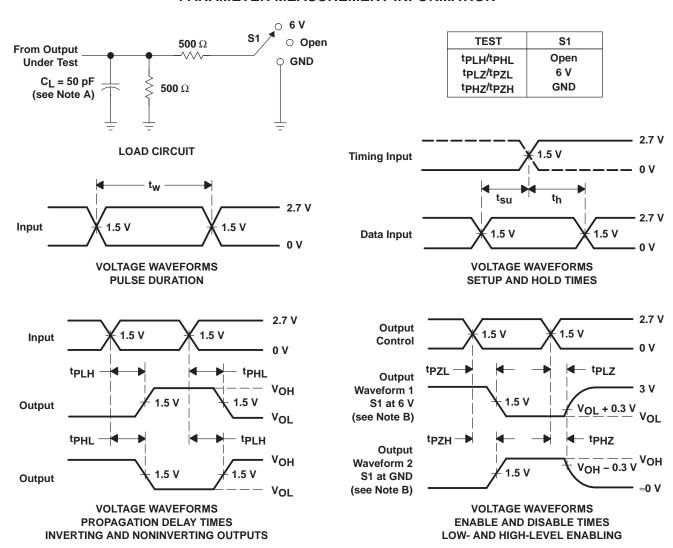
				SN54L\	/TH646			SN7	4LVTH	646		
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> =		VCC =	2.7 V		CC = 3.3 ± 0.3 V	V	VCC =	2.7 V	UNIT
			MIN	MAX	MIN	MAX	MIN	TYP <sup>†</sup>	MAX	MIN	MAX	
f <sub>max</sub>			150		150		150			150		MHz
<sup>t</sup> PLH	CLKBA or	A or D	1	5.3		5.9	1.8	3.1	4.7		5.6	20
<sup>t</sup> PHL	CLKAB	A or B	1.5	5		5.9	1.8	3.1	4.7		5.6	ns
<sup>t</sup> PLH	A D	D A	1	4.9		5.6	1.3	2.3	3.5		4.1	
<sup>t</sup> PHL	A or B	B or A	1.2	4.8		5	1.3	2.4	3.5		4.1	ns
<sup>t</sup> PLH	CDA or CADT	A == D	1	5.3		6.3	1.5	3	4.9		6	
<sup>t</sup> PHL	SBA or SAB‡	A or B	1.3	5.3		6.3	1.5	3.3	4.9		6	ns
<sup>t</sup> PZH	<u>OE</u>	A D	1	5.4		6.7	1.1	3.1	5.2		6.5	
<sup>t</sup> PZL	OE	A or B	1	5.6		6.7	1.1	3.4	5.2		6.5	ns
<sup>t</sup> PHZ	ŌĒ	A D	1.7	6.3		6.5	2.3	3.9	5.5		6.1	
tPLZ	OE	A or B	2.2	6.3		6.5	2.3	4	5.5		5.9	ns
<sup>t</sup> PZH	D.D.	A == D	1.2	5.6		6.8	1.3	3.4	5.2		6.6	
t <sub>PZL</sub>	DIR	A or B	1.2	6.7		6.8	1.3	3.6	5.2		6.6	ns
<sup>t</sup> PHZ	DIR	A or B	1.1	7.2		8.1	1.5	3.2	5.6		6.7	ns
<sup>t</sup> PLZ	DIK	AUIB	1.4	6.1		6.6	1.5	3.8	5.6		6.3	115

<sup>&</sup>lt;sup>†</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>&</sup>lt;sup>‡</sup> These parameters are measured with the internal output state of the storage register opposite that of the bus input.

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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \,\Omega$ ,  $t_f \leq 2.5 \,$ ns.  $t_f \leq 2.5 \,$ ns.
- D. The outputs are measured one at a time, with one transition per measurement.
- E. All parameters and waveforms are not applicable to all devices.

Figure 2. Load Circuit and Voltage Waveforms



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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	<b>RoHS</b> (3)	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
5962-9674801Q3A	Active	Production	LCCC (FK)   28	42   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9674801Q3A SNJ54LVTH 646FK
SN74LVTH646DW	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH646
SN74LVTH646DW.B	Active	Production	SOIC (DW)   24	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LVTH646
SN74LVTH646PWR	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH646
SN74LVTH646PWR.B	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH646
SN74LVTH646PWRG4	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH646
SN74LVTH646PWRG4.B	Active	Production	TSSOP (PW)   24	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	LXH646
SNJ54LVTH646FK	Active	Production	LCCC (FK)   28	42   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9674801Q3A SNJ54LVTH 646FK

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE OPTION ADDENDUM**

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Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

#### OTHER QUALIFIED VERSIONS OF SN54LVTH646, SN74LVTH646:

Catalog: SN74LVTH646

Military: SN54LVTH646

NOTE: Qualified Version Definitions:

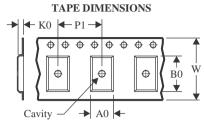
- Catalog TI's standard catalog product
- Military QML certified for Military and Defense Applications

# **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LVTH646PWR	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1
SN74LVTH646PWRG4	TSSOP	PW	24	2000	330.0	16.4	6.95	8.3	1.6	8.0	16.0	Q1

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### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LVTH646PWR	TSSOP	PW	24	2000	353.0	353.0	32.0
SN74LVTH646PWRG4	TSSOP	PW	24	2000	353.0	353.0	32.0

# **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



#### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74LVTH646DW	DW	SOIC	24	25	506.98	12.7	4826	6.6
SN74LVTH646DW.B	DW	SOIC	24	25	506.98	12.7	4826	6.6

# FK (S-CQCC-N\*\*)

# LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004





SMALL OUTLINE PACKAGE



#### NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

  2. This drawing is subject to change without notice.

  3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
- 5. Reference JEDEC registration MO-153.



SMALL OUTLINE PACKAGE



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SMALL OUTLINE PACKAGE



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



DW (R-PDSO-G24)

# PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters). Dimensioning and tolerancing per ASME Y14.5M-1994.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



DW (R-PDSO-G24)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Refer to IPC7351 for alternate board design.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



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